## 1. Package summary

| | |
|---|---|
| **Terminal position code** | P (perpendicular) |
| **Package type descriptive code** | RDBS27P |
| **Package style descriptive code** | RDBS (right-angle DIL-bent-SIL) |
| **Mounting method type** | T (through-hole mount) |
| **Issue date** | 17-1-2018 |
| **Manufacturer package code** | 98ASA01167D |

**Table 1. Package summary**

| Symbol | Parameter | | Min | Typ | Nom | Max | Unit |
|---|---|---|---|---|---|---|---|
| D | package length | | - | - | 29.1 | - | mm |
| E | package width | | - | - | 15.9 | - | mm |
| $A_2$ | package height | | - | - | 4.5 | - | mm |
| e | nominal pitch | | - | - | 1 | - | mm |
| $n_2$ | actual quantity of termination | | - | - | 27 | - | A/A |

## 2. Package outline



9.27 MAX
8.87 MIN

7.22 MAX
6.82 MIN

EXPOSED PAD

1          27

26X 1

TOP VIEW

D

D

E          1          27          E

B

3    16.2
     15.6

2X    3.55
      3.25

24.8
24.4

29.3
28.9          A

3

BOTTOM VIEW

© NXP B.V. ALL RIGHTS RESERVED

DATE: 27 MAR 2018

| MECHANICAL OUTLINE<br>PRINT VERSION NOT TO SCALE | STANDARD:<br>NON JEDEC | DRAWING NUMBER:<br>SOT1961-1 | REVISION:<br>A | |

**Fig. 1.    Package outline SOT1961-1**
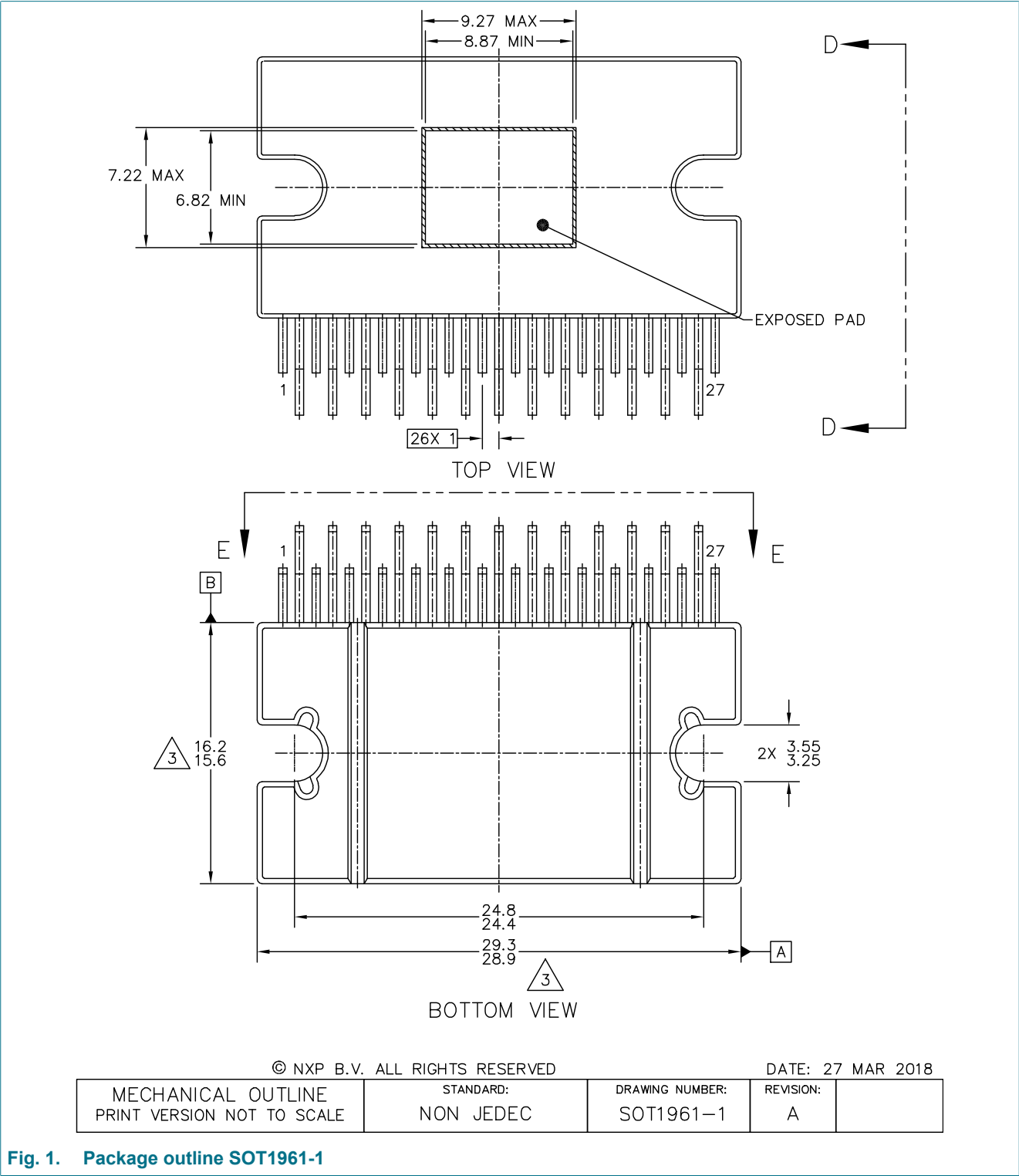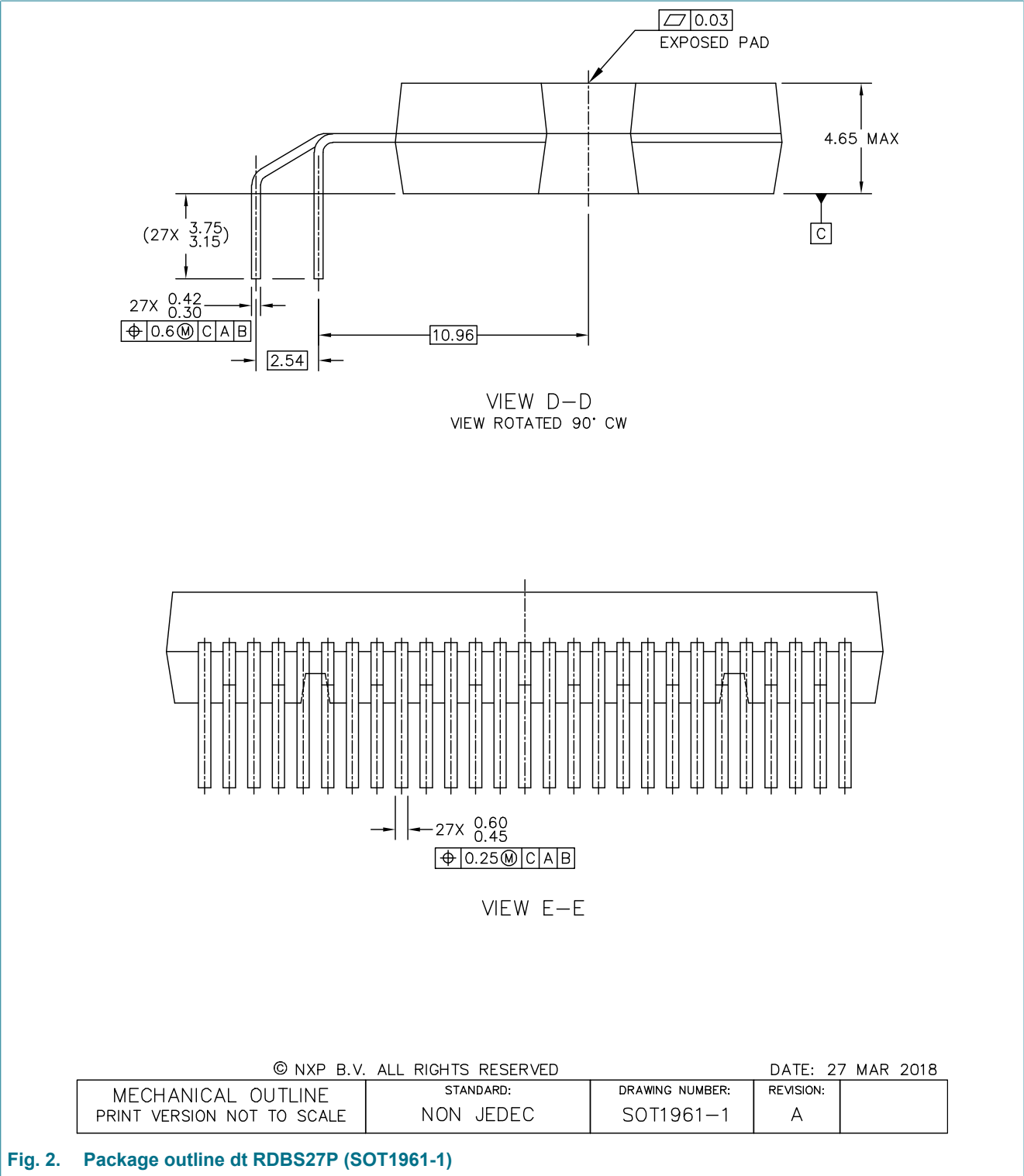
**RDBS27P, right-angle DIL-bent-SIL package, 27 terminals, 1.0 mm pitch, 15.9 mm x 29.1 mm x 4.5 mm body**



VIEW D—D
VIEW ROTATED 90° CW

VIEW E—E

© NXP B.V. ALL RIGHTS RESERVED

DATE: 27 MAR 2018

| MECHANICAL OUTLINE<br>PRINT VERSION NOT TO SCALE | STANDARD:<br>NON JEDEC | DRAWING NUMBER:<br>SOT1961—1 | REVISION:<br>A | |

**Fig. 2.    Package outline dt RDBS27P (SOT1961-1)**

NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M−1994.

△3. THIS DIMENSION INCLUDES MOLD PROTRUSION.

DATE: 27 MAR 2018

| MECHANICAL OUTLINE<br>PRINT VERSION NOT TO SCALE | STANDARD:<br>NON JEDEC | DRAWING NUMBER:<br>SOT1961−1 | REVISION:<br>A | |
|---|---|---|---|---|

**Fig. 3.    Package outline note RDBS27P (SOT1961-1)**

## 3. Legal information

### Disclaimers

**Limited warranty and liability** — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. NXP Semiconductors takes no responsibility for the content in this document if provided by an information source outside of NXP Semiconductors.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the *Terms and conditions of commercial sale* of NXP Semiconductors.

**Right to make changes** — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

# 4. Contents

SOT1961-1

All information provided in this document is subject to legal disclaimers.

© NXP B.V. 2018. All rights reserved

**Package information**

**7 May 2018**

**6 / 6**